Silicon Carbide (SiC) Schottky Diode - EliteSiC, 20 A, 650 V, D2, TO-247-3L

FFSH2065BDN

Description

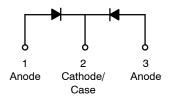
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

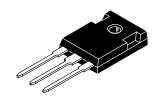
- Max Junction Temperature 175°C
- Avalanche Rated 49 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverters, UPS
- Power Switching Circuit

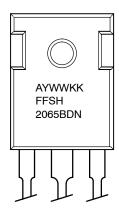


Schottky Diode



TO-247-3LD CASE 340CX

MARKING DIAGRAM



A = Assembly Plant Code
YWW = Date Code (Year & Week)
KK = Lot Traceability Code
FFSH2065BDN = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	Reverse Voltage		V
E _{AS}	Single Pulse Avalanche Energy	ngle Pulse Avalanche Energy (Note 1)		mJ
l _F	Continuous Rectified Forward Current @ T _C <	Continuous Rectified Forward Current @ T _C < 136°C		А
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	650	Α
		T _C = 150°C, 10 μs	570	Α
I _{F,SM}	Non-Repetitive Forward Surge Current $T_C = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	42	А
Ptot	Power Dissipation	T _C = 25°C	65	W
		T _C = 150°C	11	W
T _J , T _{STG}	Operating and Storage Temperature Range TO247 Mounting Torque, M3 Screw		-55 to +175	°C
			60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	2.3*/1.2**	°C/W

^{*} Per Leg, ** Per Device

ELECTRICAL CHARACTERISTICS ($T_C = 25$ °C unless otherwise noted (per leg))

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V_{F}	Forward Voltage	I _F = 10 A, T _C = 25°C	_	1.38	1.7	V
		I _F = 10 A, T _C = 125°C	_	1.6	2.0	
		I _F = 10 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	V _R = 650 V, T _C = 25°C	-	0.5	40	μΑ
		V _R = 650 V, T _C = 125°C	-	1	80	
		V _R = 650 V, T _C = 175°C	-	2	160	
Q_{C}	Total Capacitive Charge	V = 400 V	-	25	=	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	421	_	pF
		V _R = 300 V, f = 100 kHz	-	40	-	
		V _R = 600 V, f = 100 kHz	-	34	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part	Number	Top Marking	Package	Shipping
FFSH	12065BDN	FFSH2065BDN	TO-247-3LD (Pb-Free / Halogen Free)	30 Units / Tube

^{*} Per Leg, ** Per Device 1. E_{AS} of 49 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 14$ A, V = 50 V.

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ UNLESS OTHERWISE NOTED (PER LEG)})$

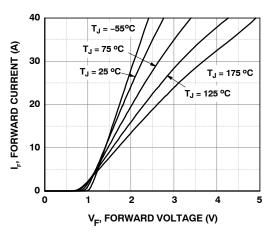


Figure 1. Forward Characteristics

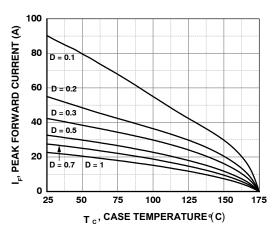


Figure 3. Current Derating

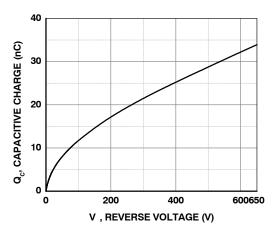


Figure 5. Capacitive Charge vs. Reverse Voltage

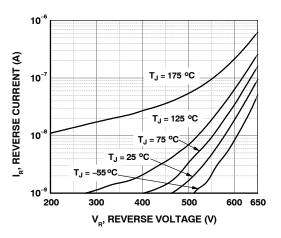


Figure 2. Reverse Characteristics

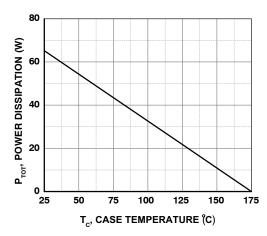


Figure 4. Power Derating

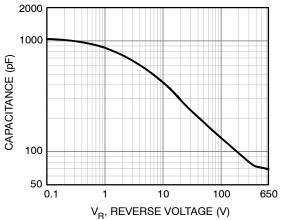


Figure 6. Capacitive vs. Reverse Voltage

TYPICAL CHARACTERISTICS

(T_J = 25°C UNLESS OTHERWISE NOTED)

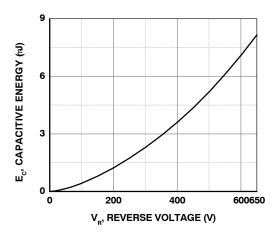


Figure 7. Capacitance Stored Energy

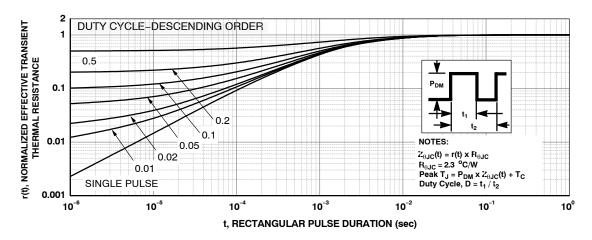


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

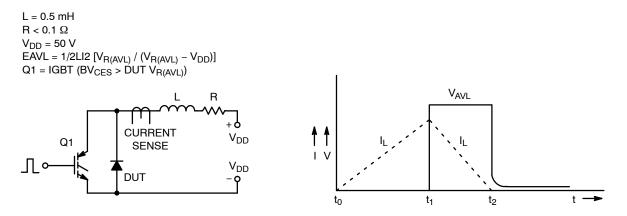
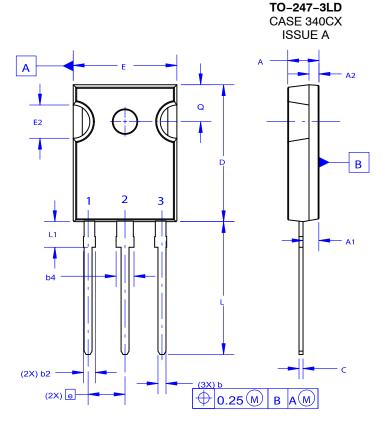


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

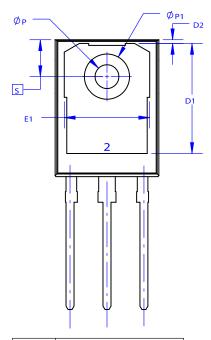
PACKAGE DIMENSIONS



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1. E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	2	~		
D2	0.51	0.93	1.35		
E1	12.81	?	~		
ØP1	6.60	6.80	7.00		

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